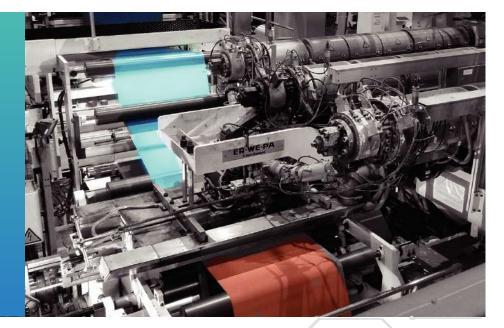


#### TECHNICAL DATASHEET

BlueFlame BF300-120-H/H BF300-60-H/H BF300-30-H/H BF300-20-H/H BF300-16-H/H



PCB Laminate for RF&MW Applications

BlueFlame is based on PureBlue proprietary polymer chemistry and continuous lamination technology.

Both the process and the substrate structure and composition are protected by existing patents and patent pendings.



# PURE 2 LUE

BlueFlame BF300-120-H/H BF300-60-H/H BF300-30-H/H BF300-20-H/H BF300-16-H/H

The BlueFlame laminate is designed to meet most demanding application scenarios.

The absolute glass fiber free system delivers unique uniform (X-Y-Z) low CTE of 35-45 ppm/°C.

Multiple short time expositions to heat of 330 °C, capacity to operate at above 200 °C.

The proprietary to PureBlue continuous lamination process of high throughput secures tight thickness tolerance and very narrow fluctuation of dielectric constant.

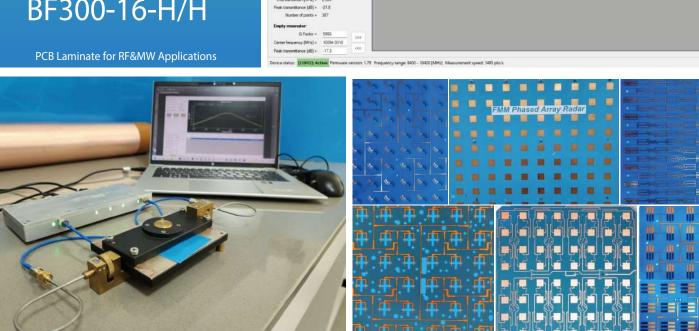
The BF300 polymer compound features highly cross-linked polyolefin system designed for critical microwave components, antennas, power amplifiers and subassemblies.

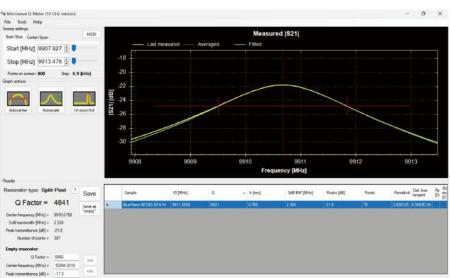
Superior mechanical and electrical performance make the BF300 laminate system the material of choice for your lowest loss high frequency applications.

The isotropic subtrate structure secures substantial advantage in PIM readings vs. anisotropic analogies.

The highest impact was recorded with dense PTH designs, better than -163 dBc under dynamic test and better than -170 dBc under static one.

PIM designated lowest profile foils apply in our performance-on-demand product versions.





#### TECHNICAL DATASHEET







# **Typical Specification Values**

Property	IPC-TM 650 or ASTM	Units	Value	Condition / Remarks	
Dielectric Constant	IPC 2.5.5.2		3.00±0.05	@10 GHz 23 ℃	
Dissipation Factor			0.0008		
Peel Strength	IPC 2.4.8	N/mm	1.5-2.1	Typical	
Moisture Absorption	IPC 2.6.2.1	wt. %	<0.06	Typical	
Volume Resistivity	IPC 2.5.17.1	MΩ - cm	>107		
Surface Resistivity	IPC 2.5.17.1	MΩ - cm	>107		
Dielectric Strength	IPC 2.5.6	kV/mm	19.7		
Flexural Strength, min	IPC 2.4.4	GPa	4		
Thermal Conductivity	ASTM C518	W/m-K	0.35		
x-y-z CTE, (-45 to 250°C)	DMA/TMA	Ppm/°C	<45		
Flammability	UL-94		НВ		
Recommended operational temperature range		°C	-45 to +150	For operation outside this temperature range please ask your technical contact.	
After Etch Substrate Contraction,	Recommended	0/	0.18 MD		
max.	compensation	%	0.15 TD		
RoHS and Lead Free compatibility			Compatible		





## **Electro Deposited HTE Copper Foil Specifications**

Typical copper cladding is 15 μ HTE specified below. Other foil thickness - 12, 18, 24 and 35 may apply per demand. Other foil types may apply - reverse treated, rolled. Copper foil may be replaced with aluminum rolled. Aluminum thickness - 20 to 50 μ

Nominal thickness, μm	Area weight, g/m	2	Tensile strength N/mm2	٦,	Elongation, %		Resistivity at 20 °C, Ohm g/m2	
15± 1	125 ± 10		> 245		> 3		< 0,162	
Feature		Unit			Gauge		IPC	
					25μ	IPC-	4562	IPC-MF-650
Shiny side roughness, Ra			μ		0,2-0,4	),2-0,4 3.5.6		2.2.17
Matt side roughness, Rz		μ			4-5		4.5	2.2.17
Tensile strength, room temperature		MPa,			> 276	3.5.1		2.4.18
Elongation, room temperature		%			> 10	3.5.3		2.4.18
Solderability		Meets requirements of IPC-4562			3.6.3		2.4.12	

### Panel Thickness (excluding copper foil)

- BF300-120-H/H 3048  $\mu$  / 0.120" with a tolerance of  $\pm$  75  $\mu$
- BF300-600-H/H 508  $\mu$  / 0.060" with a tolerance of  $\pm$  40  $\mu$
- BF300-30-H/H 760  $\mu$  / 0.030" with a tolerance of ± 25  $\mu$
- BF300-20-H/H 508  $\mu$  / 0.020" with a tolerance of ± 15  $\mu$
- BF300-16-H/H 406  $\mu$  / 0.016" with a tolerance of  $\pm$  12  $\mu$

## Panel Dimensions

Standard 608X1220 mm

• Panel length may be increased upon arrangement to maximize the yield for massive orders upon arrangement.

Lowest-loss PCB Laminates PureBlue Zhongshan Technology Co. Ltd. Zhongshan, Guangdong, China Tel: +33 781523052 Email: manuel@purebluerf.com